

Version with Markings to Show Changes Made

2. A wiring board as claimed in claim [2]1, wherein:
a thickness of said conductive member is $\frac{1}{2}$ or more of that of said insulating substrate.

[40.] 39. A process for the production of a wiring board as claimed in claim 37, wherein:

a step for forming said conductive member is effected by forming a copper (Cu) plating or a nickel (Ni) plating in accordance with electroplating method.

[41.] 40. A process for the production of a wiring board as claimed in claim 38, wherein:

a step for forming said conductive member is effected by forming a copper (Cu) plating or a nickel (Ni) plating in accordance with electroplating method.

[42.] 41. A process for the production of a wiring board as claimed in claim 37, wherein:

a step for forming said conductive member is effected by forming a nickel (Ni) plating in accordance with electroless plating method.

[43.] 42. A process for the production of a wiring board as claimed in claim 38, wherein:

a step for forming said conductive member is effected by forming a nickel (Ni) plating in accordance with electroless plating method.